

L Number	Hits	Search Text	DB	Time stamp
5	3778	CMOS with image with sensor	USPAT; US-PGPUB	2004/09/29 15:23
6	10	(CMOS with image with sensor) and ((resist PR photoresist) near3 ash\$3)	USPAT; US-PGPUB	2004/09/29 15:23
7	0	((("20040182822" "20040087153" "20040077160" "20040078139" "200400725322" "200400301091"	USPAT; US-PGPUB	2004/09/29 15:23
8	46	and ((rapid near3 thermal near3 (anneal\$3 process\$3)) image with sensor) and ((rapid near3 thermal near3 (anneal\$3 process\$3)) RTP RTA)	USPAT; US-PGPUB	2004/09/29 14:26
9	5043	remov\$3 near10 (resist PR photoresist) near10 ash\$3	USPAT; US-PGPUB	2004/09/29 14:27
10	1744	(remov\$3 near10 (resist PR photoresist) near10 ash\$3) and trench	USPAT; US-PGPUB	2004/09/29 14:27
11	347	((remov\$3 near10 (resist PR photoresist) near10 ash\$3) and trench) and CMOS	USPAT; US-PGPUB	2004/09/29 15:23
12	1959	(((((trench recess groove hole open\$4) and pixel) and (photodiode (photo near3 diode) diode)) and (dop\$4 implant\$3)) and (heat\$3 anneal\$3)) and (etch\$3 pattern\$4)) and (pr photoresist (photo near3 resist) resist)	USPAT; US-PGPUB	2004/09/29 15:22
13	0	(((((trench recess groove hole open\$4) and pixel) and (photodiode (photo near3 diode) diode)) and (dop\$4 implant\$3)) and (heat\$3 anneal\$3)) and (etch\$3 pattern\$4)) and (pr photoresist (photo near3 resist) resist)	EPO; JPO; DERWENT; IBM_TDB	2004/09/29 15:23
14	849	(((((trench recess groove hole open\$4) and pixel) and (photodiode (photo near3 diode) diode)) and (dop\$4 implant\$3)) and (heat\$3 anneal\$3)) and (etch\$3 pattern\$4)) and (pr photoresist (photo near3 resist) resist)) and CMOS	USPAT; US-PGPUB	2004/09/29 15:23
15	1709	CMOS and image and sensor	EPO; JPO; DERWENT; IBM_TDB	2004/09/29 15:23
17	40	(CMOS and image and sensor) and (resist PR photoresist)	EPO; JPO; DERWENT; IBM_TDB	2004/09/29 15:24